



July 20, 2017

NEWS RELEASE

Increase in Production Capacity of Electro-deposited Copper Foil for High-Frequency Circuit Boards

-To increase VSP[®] production capacity by 1.6 times to 275 tons per month in Taiwan Plant-

Mitsui Mining & Smelting Co., Ltd. (President: Keiji Nishida; “Mitsui Kinzoku,” hereinafter) is pleased to announce that it has decided to increase monthly production of its VSP[®] copper foil for high-frequency circuit boards to 275 tons.

Mitsui Kinzoku’s VSP[®] copper foil for high-frequency circuit boards has been widely recognized in the market as the ideal copper foils for its excellent surface flatness with very low profile copper nodules on the surface that provides low transmission loss at high frequency signal band.

VSP[®] is the core product of Mitsui Kinzoku’s Taiwan plant (namely Taiwan Copper Foil Co., Ltd.) and has mainly been used at high-frequency circuit boards for communication infrastructure equipment (severs, routers, base stations and others) to enable low loss and high speed printed circuit design . Since last year, the demand volume has grown markedly due to high speed and data traffic on the increase in network. To meet this strong demand, Mitsui Kinzoku will partially upgrade the existing production line and expand electro-deposited cells at its Taiwan plant to increase the monthly production capacity from 175 to 275 tons. These facilities will sequentially come online from April 2018.

Mitsui Kinzoku is committed to offer stable quality and ensure adequate supply to its customers under the slogan “Material Intelligence”

[Inquiries]

Investor Relations and Corporate Communications Department,

Corporate Planning & Control Sector

Mitsui Mining & Smelting Co., Ltd.

Email: PR@mitsui-kinzoku.co.jp



Conventional copper foil



VSP® foil

Photo: Copper foil surface reflecting an apple mango

*VSP® features excellent surface flatness like a mirror

(Reference)

Taiwan Copper Foil Co., Ltd.

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| (1) Name | Taiwan Copper Foil Co., Ltd. |
| (2) Location | No. 150, Chenggong 3rd Road, Nantou City, Nantou County, 540, R.O.C |
| (3) President | Hirotooshi Fukumoto |
| (4) Established | November 1980 |
| (5) Capital | NTD800M |
| (6) Investment | Mitsui Kinzoku (95%) |
| (7) Business Activities | Manufacturing of copper foil for printed circuit boards |